### TinyLogic HS 2-Input OR Gate

### NC7S32

#### Description

The NC7S32 is a single 2–Input high performance CMOS OR Gate. Advanced Silicon Gate CMOS fabrication assures high speed and low power circuit operation over a broad  $V_{CC}$  range. ESD protection diodes inherently guard both inputs and output with respect to the  $V_{CC}$ and GND rails. Three stages of gain between inputs and outputs assures high noise immunity and reduced sensitivity to input edge rate.

#### Features

- Space Saving SOT23-5, SC-74A and SC-88A 5-Lead Packages
- Ultra Small MicroPak<sup>TM</sup> Leadless Package
- High Speed:  $t_{PD} = 3.5$  ns Typ
- Low Quiescent Power:  $I_{CC} < 1 \mu A$
- Balanced Output Drive: 2 mA I<sub>OL</sub>, -2 mA I<sub>OH</sub>
- Broad V<sub>CC</sub> Operating Range: 2 V 6 V
- Balanced Propagation Delays
- Specified for 3 V Operation
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



Figure 1. Logic Symbol

	SIP6 CASE 127EB	тткк хүг
	Pin 1	~
	SC-74A CASE 318BQ	0 
	SOT23–5 CASE 527AH	
	SC-88A CASE 419A-02	S32M• 0 •
TT, 7S32, S32 KK XY Z M	? = Specific Device C = 2-Digit Lot Run T = 2-Digit Date Cod = Assembly Plant C = Date Code*	raceability Code e Format
*Date Code	orientation and/or	position may

\*Date Code orientation and/or position may vary depending upon manufacturing location.

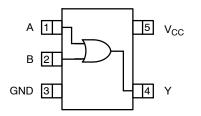
#### **ORDERING INFORMATION**

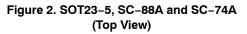
See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 5.

MARKING DIAGRAMS

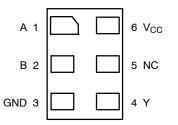
### **Pin Configurations**





#### **PIN DESCRIPTIONS**

Pin Name	Description
A, B	Inputs
Y	Output
NC	No Connect



#### Figure 3. MicroPak (Top Through View)

#### FUNCTION TABLE (Y = A + B)

Inp	Output	
А	В	Y
L	L	L
L	Н	Н
Н	L	Н
Н	Н	Н

H = HIGH Logic Level L = LOW Logic Level

Symbol	Parameter           Supply Voltage		Min	Мах	Unit
V <sub>CC</sub>			-0.5	6.5	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < 0 V	-	-20	mA
		$V_{IN} > V_{CC}$	-	+20	
V <sub>IN</sub>	DC Input Voltage		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < 0 V	-	-20	mA
		V <sub>OUT</sub> > V <sub>CC</sub>	-	+20	
V <sub>OUT</sub>	DC Output Voltage		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>OUT</sub>	DC Output Source or Sink Current		-	±12.5	mA
$I_{\rm CC}$ or $I_{\rm GND}$	DC V <sub>CC</sub> or Ground Current per Out	tput Pin	-	±25	mA
T <sub>STG</sub>	Storage Temperature		-65	+150	°C
TJ	Junction Temperature		-	+150	°C
ΤL	Lead Temperature (Soldering, 10 Seconds)		-	+260	°C
PD	Power Dissipation in Still Air	SC-74A / SOT23-5	-	390	mW
		SC-88A	-	332	
		MicroPak-6	-	812	

#### **ABSOLUTE MAXIMUM RATINGS**

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Conditions	Min	Мах	Unit
V <sub>CC</sub>	Supply Voltage		2.0	6.0	V
V <sub>IN</sub>	Input Voltage		0	V <sub>CC</sub>	V
V <sub>OUT</sub>	Output Voltage		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	t <sub>r</sub> , t <sub>f</sub> Input Rise and Fall Times	V <sub>CC</sub> at 2.0 V	0	20	ns/V
		V <sub>CC</sub> at 3.0 V	0	20	
		V <sub>CC</sub> at 4.5 V	0	10	
		V <sub>CC</sub> at 6.0 V	0	5	
$\theta_{JA}$	Thermal Resistance	SC-74A / SOT23-5	-	320	°C/W
		SC-88A	-	377	
		MicroPak-6	-	154	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability. 1. Unused inputs must be held HIGH or LOW. They may not float.

#### **DC ELECTICAL CHARACTERISTICS**

				-	Γ <sub>A</sub> = +25°C	)	T <sub>A</sub> = -40	to +85°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	HIGH Level Input Voltage	2.0 3.0 – 6.0		1.50 0.7 V <sub>CC</sub>			1.50 0.7 V <sub>CC</sub>		V
V <sub>IL</sub>	LOW Level Input Voltage	2.0 3.0 – 6.0			-	0.50 0.3 V <sub>CC</sub>	- -	0.50 0.3 V <sub>CC</sub>	V
V <sub>OH</sub>	HIGH Level Output Voltage	2.0 3.0 4.5 6.0		1.90 2.90 4.40 5.90	2.0 3.0 4.5 6.0	- - - -	1.90 2.90 4.40 5.90	- - - -	V
		3.0 4.5 6.0	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -1.3 \text{ mA}$ $I_{OH} = -2.0 \text{ mA}$ $I_{OH} = -2.6 \text{ mA}$	2.68 4.18 5.68	2.85 4.35 5.85	- - -	2.63 4.13 5.63		V
V <sub>OL</sub>	LOW Level Output Voltage	2.0 3.0 4.5 6.0		- - - -	0.0 0.0 0.0 0.0	0.10 0.10 0.10 0.10	- - - -	0.10 0.10 0.10 0.10	V
		3.0 4.5 6.0	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 1.3 \text{ mA}$ $I_{OL} = 2.0 \text{ mA}$ $I_{OL} = 2.6 \text{ mA}$	- - -	0.1 0.1 0.1	0.26 0.26 0.26	- - -	0.33 0.33 0.33	V
I <sub>IN</sub>	Input Leakage Current	6.0	V <sub>IN</sub> = V <sub>CC</sub> , GND	-	-	±0.1	-	±1.0	μΑ
I <sub>CC</sub>	Quiescent Supply Current	6.0	V <sub>IN</sub> = V <sub>CC</sub> , GND	-	-	1.0	-	10.0	μA

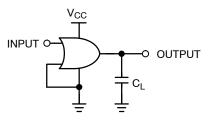


#### AC ELECTRICAL CHARACTERISTICS

				T <sub>A</sub> = +25°C		)	T <sub>A</sub> = −40 to +85°C		
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub> ,	Propagation Delay (Figure 4, 6)	5.0	C <sub>L</sub> = 15 pF	-	3.5	15	-	-	ns
t <sub>PHL</sub>		2.0 3.0 4.5 6.0	C <sub>L</sub> = 50 pF	- - -	20 12 8 7	100 27 20 17	- - -	125 35 25 21	ns
t <sub>TLH</sub> ,	Output Transition Time	5.0	C <sub>L</sub> = 15 pF	-	3.0	10	-	-	ns
t <sub>THL</sub>	(Figure 4, 6)	2.0 3.0 4.5 6.0	C <sub>L</sub> = 50 pF	- - - -	25 16 11 9	125 35 25 21	- - - -	155 45 30 26	ns
C <sub>IN</sub>	Input Capacitance	Open		-	2	10	-	10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Figure 5)	5.0	(Note 2)	-	6	_	_	-	pF

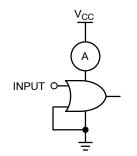
2.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle.  $C_{PD}$  is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub> = ( $C_{PD}$ ) (V<sub>CC</sub>) ( $f_{IN}$ ) + (I<sub>CC</sub>static).

#### AC Loading and Waveforms



 $C_L$  includes load and stray capacitance Input PRR = 1.0 MHz;  $t_W$  = 500 ns

#### Figure 4. AC Test Circuit



Input = AC Waveforms; PRR = Variable; Duty Cycle = 50%.

Figure 5. I<sub>CCD</sub> Test Circuit

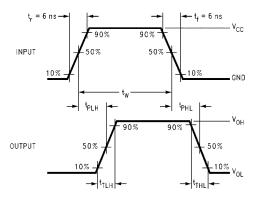


Figure 6. AC Waveforms



#### **ORDERING INFORMATION**

Part Number	Top Mark	Package Description	Shipping <sup>†</sup>
NC7S32M5X	7S32	SC-74A	3000 / Tape & Reel
NC7S32P5X	S32	SC-88A	3000 / Tape & Reel
NC7S32L6X	TT	SIP6, MicroPak	5000 / Tape & Reel

#### **DISCONTINUED** (Note 3)

NC7S32M5X-L22090	7S32	SOT23-5	3000 / Tape & Reel
NC7S32L6X-L22175	TT	SIP6, MicroPak	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

3. **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on <u>www.onsemi.com</u>.

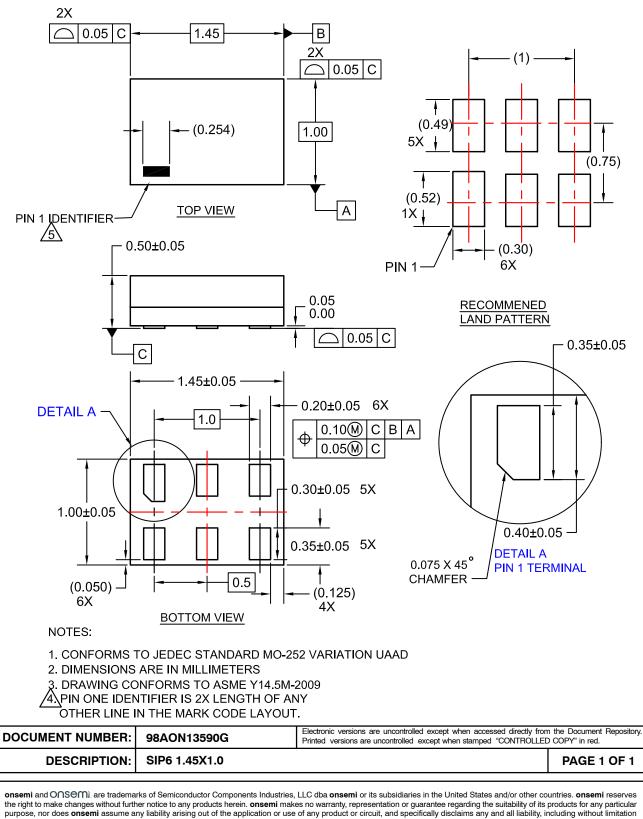
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SIP6 1.45X1.0 CASE 127EB ISSUE O

DATE 31 AUG 2016



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#### SC-74A-5 3.00x1.50x0.95, 0.95P CASE 318BQ **ISSUE C** DATE 26 FEB 2024 NOTES: 5X b ⊕ 0.20 M C A B DIMENSIONING AND TOLERANCING CONFORM TO ASME 1. Y14.5-2018. 2. ALL DIMENSION ARE IN MILLIMETERS (ANGLES IN DEGREES). В 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, Ē 4 E1 PROTRUSIONS OF GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. MILLIMETERS ○ 0.15 C DIM NOM. MIN. MAX. 2X е 0.90 1.00 1.10 А A A1 0.01 0.18 0.10 0.95 REF Α2 TOP VIEW 0.25 0.37 0.50 b DETAIL A (A2) 0.10 0.18 0.26 С Α D 2.85 3.00 3.15 Ε 2.75 BSC E1 1.35 1.50 1.65 0.05 C SEATING е 0.95 BSC Α1 Ċ PLANE END VIEW SIDE VIEW L 0.20 0.40 0.60 L1 0.62 REF 0.25 BSC 12 GAUGE PLANE L2 5° 10° Θ 0° 1.90 0.95 Ð, (L1)"A" DETAIL SCALE 2:1 2.40 GENERIC **MARKING DIAGRAM\*** 1.00 0.70 XXX M= -O RECOMMENDED MOUNTING FOOTPRINT\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING XXX = Specific Device Code = Date Code Μ TECHNIQUES REFERENCE MANUAL, SOLDERRM/D. = Pb-Free Package (Note: Microdot may be in either location) \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •" may or may not be present. Some products may not follow the Generic Marking. Electronic versions are uncontrolled except when accessed directly from the Document Repository. **DOCUMENT NUMBER:** 98AON66279G Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. **DESCRIPTION:** SC-74A-5 3.00x1.50x0.95, 0.95P PAGE 1 OF 1

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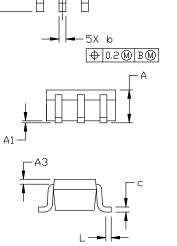
DATE 11 APR 2023



#### SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

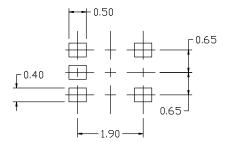
NDTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. 419A-01 DBSDLETE. NEW STANDARD 419A-02
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.



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#### RECOMMENDED MOUNTING FOOTPRINT

\* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

DIM	MI	LLIMETE	RS		
MIM	MIN.	NDM,	MAX.		
А	0.80	0.95	1.10		
A1			0.10		
AЗ		0.20 REF			
b	0.10	0.20	0.30		
С	0.10		0.25		
D	1.80	2.00	2.20		
E	2.00	2.10	2,20		
E1	1.15	1.25	1.35		
e		0.65 BSC			
L	0.10	0.15	0.30		

#### **GENERIC MARKING**





\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

M = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

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STYLE 6: PIN 1. EMITTER 2 2. BASE 2 3. EMITTER 1 4. COLLECTOR 5. COLLECTOR 2/BASE	STYLE 7: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 1 5. COLLECTOR	STYLE 8: PIN 1. CATHODE 2. COLLECTOR 3. N/C 4. BASE 5. EMITTER	STYLE 9: PIN 1. ANODE 2. CATHODE 3. ANODE 4. ANODE 5. ANODE	Note: Please refer to style callout. If style to out in the datasheet r datasheet pinout or p	ype is not called efer to the device
STYLE 1: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 5. COLLECTOR	STYLE 2: PIN 1. ANODE 2. EMITTER 3. BASE 4. COLLECTOR 5. CATHODE	STYLE 3: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. CATHODE 1	STYLE 4: PIN 1. SOURCE 1 2. DRAIN 1/2 3. SOURCE 1 4. GATE 1 5. GATE 2	STYLE 5: PIN 1. CATHODE 2. COMMON ANOD 3. CATHODE 2 4. CATHODE 3 5. CATHODE 4	E

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PIN 1

REFERENCE

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DATE 09 JUN 2021

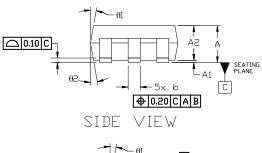
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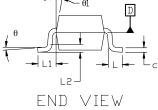
В

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 19894
- 2. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM D.
- 5. DIMENSION 'b' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE 'b' DIMENSION AT MAXIMUM MATERIAL CONDITION. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN 0.07mm.



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TOP VIEW



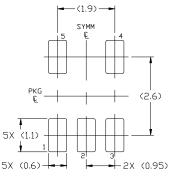
GENERIC MARKING DIAGRAM\*



XXX = Specific Device CodeM = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

MILLIMETERS			
MIN.	NDM.	MAX.	
0.90	—	1.45	
0.00	_	0.15	
0.90	1.15	1.30	
0.30	_	0.50	
0.08	_	0.22	
2.90 BSC			
2.80 BSC			
1.	.60 BSC		
0	.95 BSC		
0.30	0.45	0.60	
0	.60 REF		
0	.25 REF		
0*	4°	8*	
0°	10°	15°	
0°	10°	15°	
	MIN. 0.90 0.00 0.30 0.30 22 22 1 0 0.30 0 0 0 0 0 0 0 0 0 0 0 0 0	MIN.         NUM.           0.90            0.00         1.15           0.30            0.80            2.90         BSC           1.60         BSC           0.30         0.45           0.30         0.45           0.30         0.45           0.40         REF           0.25         REF           0*         10*	



#### RECOMMENDED MOUNTING FOOTPRINT

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